



Advance Product Change Notification

201410013A

Issue Date: 15-Dec-2014

Here's your personalized quality information concerning products Digi-Key purchased from NXP.

For detailed information we invite you to view this notification online



QUALITY

Management Summary

Change notification about the release of additional PIN diodes at wafer fab DHAM (Hamburg, Germany)

Change Category

- | | | | |
|--|---|---|--|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input checked="" type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Release of PIN diodes at NXP waferfab DHAM (Hamburg, Germany)

Details of this Planned Change

Release of additional PIN diode types at NXP waferfab location DHAM (Hamburg, Germany).

The waferfab process for pindiodes at NXP manufacturing location DHAM (Hamburg, Germany) including an initial group of PIN diode types have been released per January 1st 2014.

(The PIN diode process in ICN4 (Nijmegen, The Netherlands) has been dis-continued per 31-12-12013).

With this PCN additional PIN diode types will be released at wafer manufacturing at NXP location DHAM (Hamburg Germany)

With the transfer to DHAM, there will be no change in type numbers, 12NC's, marking codes and datasheet for the concerned products with respect to the ICN4 products.

Customer products are attached to this PCN.

For your information, the additional attached product type list includes all products from this PCN.

Identification of affected products:

DHAM parts can be discriminated by the marking on the die. For the reason of smooth transition there is no change in 12NC or marking on the products but assembly fab and date code on packing and reel allow for full trace back to wafer fab details.

Why do we Plan this Change

In line with NXP manufacturing strategy

Identification of Affected Products

Product identification does not change

See above.

Product Availability

Sample Information

Sample planning follows with the final PCN

Production

Planned first shipment 31-May-2015

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

The Self Qualification Report will be ready on 27-Feb-2015.

The Final PCN is planned to be issued on: 27-Feb-2015.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 14-Jan-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name quality helpdesk BL RFSS
Position Quality engineer & Customer support
e-mail address bl.hprf.quality.helpdesk@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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